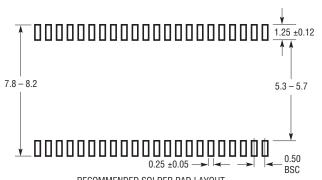
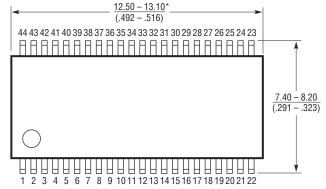
G Package 44-Lead Plastic SSOP (5.3mm)

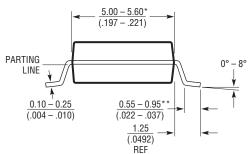
(Reference LTC DWG # 05-08-1754 Rev A)

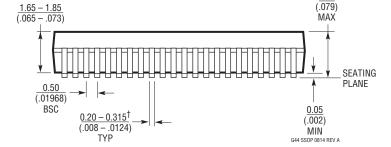




2.0

RECOMMENDED SOLDER PAD LAYOUT APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED





NOTE:

- 1.DRAWING IS NOT A JEDEC OUTLINE
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS ARE IN $\frac{\text{MILLIMETERS}}{\text{(INCHES)}}$
- ${\it 4.}~{\it DRAWING}~{\it NOT}~{\it TO}~{\it SCALE}$
- 5. FORMED LEADS SHALL BE PLANAR WITH RESPECT TO ONE ANOTHER WITHIN 0.08mm AT SEATING PLANE
- *DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DO INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH SHALL NOT EXCEED .15mm PER SIDE
- **LENGTH OF LEAD FOR SOLDERRING TO A SUBSTRATE
- †THE MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS DO NOT EXCEED 0.13mm PER SIDE